

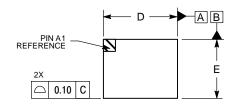
PACKAGE OUTLINE

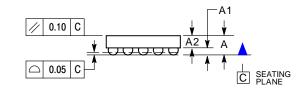


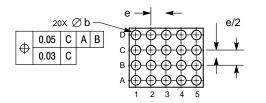
## 20 PIN FLIP-CHIP, 2.5x2.0, 0.5P CASE 499BH **ISSUE A**

DATE 22 OCT 2010

SCALE 4:1







NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS. 4. DIE COAT, 0.04 THICK, PERMISSABLE ON THIS SURFACE. DIE COAT THICKNESS IS INCLUDED IN DIMENSIONS A AND A2. onsemi and are trademarks of Semiconductor Components Industries, LLC dba onsemi or its su the right to make changes without further MALLMEETERS purpose, nor does onsemi DIM MIN MAX A 0.54 0.55

DIM	MIN	MAX
Α	0.54	0.66
A1		
A2		
b	0.29	0.34
D	2.50 BSC	
Е		
е	0.50 BSC	